

# Mosaic

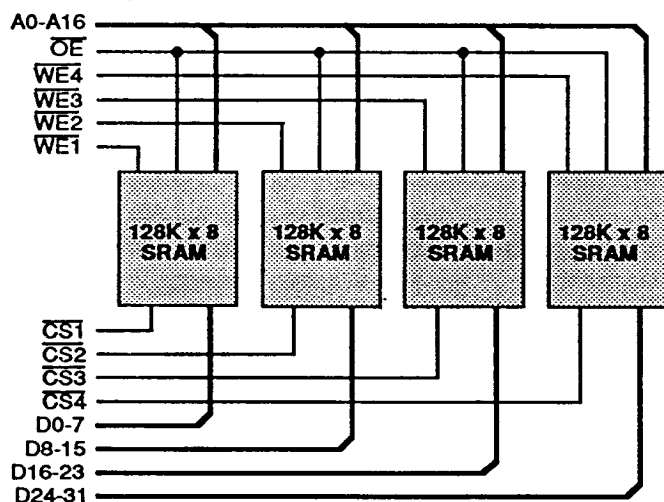
Mosaic  
Semiconductor  
Inc.

4,194,304 bit CMOS High Speed Static RAM

## Features

Fast Access times of 70/85/100/120 ns.  
Plastic Pin grid array gives 2:1 improvement over DIL.  
User Configurable as 8 / 16 / 32 bit wide.  
Operating Power 90 / 180 / 300 mW (typ).  
Low Power Standby 40  $\mu$ W (typ) -L version.  
On board decoupling capacitors.  
Directly TTL compatible inputs and outputs.  
Completely Static Operation.  
Battery Back-up capability.

## Block Diagram



## PUMA 3S4000

PUMA 3S4000-70/85/10/12

Issue 2.0 : April 1992

## ADVANCE PRODUCT INFORMATION

### Pin Definition

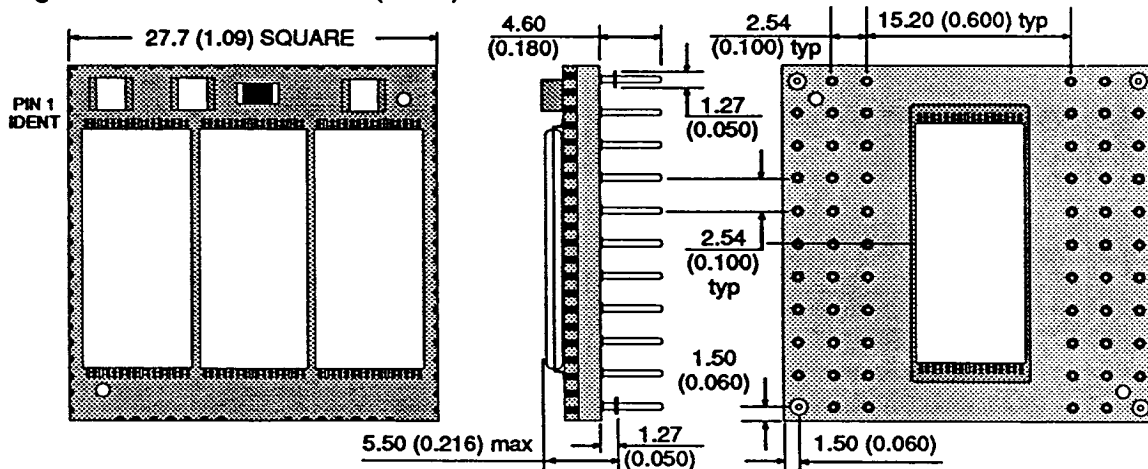
1	12	23		34	45	56
D8	WE2	D15		D24	V <sub>cc</sub>	D31
D9	CS2	D14		D25	CS4	D30
D10	GND	D13		D26	WE4	D29
A13	D11	D12		A6	D27	D28
A14	A10	OE		A7	A3	A0
A15	A11	NC		NC	A4	A1
A16	A12	WE1		A8	A5	A2
NC	V <sub>cc</sub>	D7		A9	WE3	D23
D0	CS1	D6		D16	CS3	D22
D1	NC	D5		D17	GND	D21
D2	D3	D4		D18	D19	D20
11	22	33		44	55	66

VIEW  
FROM  
ABOVE

### Pin Functions

A0 - A16 Address Inputs  
D0 - D31 Data Inputs/Outputs  
CS1-4 Chip Select  
OE Output Enable  
WE1-4 Write Enable  
NC No Connect  
V<sub>cc</sub> Power (+5V)  
GND Ground

### Package Details Dimensions in mm (inches).



**Absolute Maximum Ratings <sup>(1)</sup>**

Voltage on any pin relative to $V_{EE}$ <sup>(2)</sup>	$V_T$	-0.5V to +7	V
Power Dissipation	$P_T$	3	W
Storage Temperature	$T_{STG}$	-65 to +150	°C

Notes (1) Stresses above those listed may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the conditions above for extended periods may affect device reliability.

(2) Pulse width:- 3.5V for less than 20ns.

**Recommended Operating Conditions**

		<i>min</i>	<i>typ</i>	<i>max</i>	<i>Units</i>
Supply Voltage	$V_{CC}$	4.5	5.0	5.5	V
Input High Voltage	$V_{IH}$	2.2	-	$V_{CC}+0.3$	V
Input Low Voltage	$V_{IL}$	-0.3	-	0.8	V Note: $V_{IL}$ can be -3.0V pulse of less than 30ns.
Operating Temperature	$T_A$	0	-	70	°C
	$T_{AI}$	-40	-	85	°C (suffix I)

**DC Electrical Characteristics ( $V_{CC}=5V\pm10\%$ ,  $T_A=-40^\circ\text{C}$  to  $+85^\circ\text{C}$ )**

Parameter	Symbol	Test Condition	<i>min</i>	<i>typ</i> <sup>(1)</sup>	<i>max</i>	Unit
Input Leakage Current	$I_{LH}$	$V_{IN} = 0V$ to $V_{CC}$	-8	-	8	$\mu\text{A}$
Output Leakage Current	8 bit $I_{LO}$	$\overline{CS}^{(2)} = V_{IH}$ or $OE = V_{IH}$ , $V_{IO} = 0V$ to $V_{CC}$	-8	-	8	$\mu\text{A}$
Operating Supply Current	32 bit $I_{CC32}$	$\overline{CS}^{(2)} = V_{IL}$ , $I_{IO} = 0\text{mA}$ , $V_{IL} \geq V_{IN} \geq V_{IH}$	-	60	120	mA
	16 bit $I_{CC16}$	As above	-	32	66	mA
	8 bit $I_{CC8}$	As above	-	18	39	mA
Average Supply Current	32 bit $I_{CC32}$	$\overline{CS}^{(2)} = V_{IL}$ , Minimum cycle, $I_{IO} = 0\text{mA}$	-	180	280	mA
	16 bit $I_{CC16}$	As above	-	92	146	mA
	8 bit $I_{CC8}$	As above	-	48	79	mA
Standby Supply Current	TTL levels $I_{SB}$	$\overline{CS}^{(2)} = V_{IH}$	-	4	12	mA
	CMOS levels $I_{SB1}$	$\overline{CS}^{(2)} \geq V_{CC}-0.2V$ , $0.2V \geq V_{IN} \geq V_{CC}-0.2V$	-	0.08	8	mA
	-L part CMOS levels $I_{SB2}$	As above	-	8	400	$\mu\text{A}$
Output Voltage Low	$V_{OL}$	$I_{OL}=2.1\text{mA}$	-	-	0.4	V
Output Voltage High	$V_{OH}$	$I_{OH}=-1.0\text{mA}$	2.4	-	-	V

Notes: (1) Typical values are at  $V_{CC}=5.0V$ ,  $T_A=25^\circ\text{C}$  and specified loading.

(2)  $\overline{CS}$  above is accessed through CS1-4. These inputs must be operated simultaneously for 32 bit mode, in pairs for 16 bit mode and singly for 8 bit mode.

**Capacitance ( $V_{CC}=5V\pm10\%$ ,  $T_A=25^\circ\text{C}$ )**

Parameter	Symbol	Test Condition	<i>typ</i>	<i>max</i>	Unit
Input Capacitance	Address, OE $C_{IN1}$	$V_{IN}=0V$	-	32	pF
	Other inputs $C_{IN2}$	$V_{IN}=0V$	-	8	pF
I/O Capacitance:	8 bit mode $C_{IO}$	$V_{IO}=0V$	-	40	pF

Note: This parameter is calculated and not measured.

**AC Test Conditions**

- \*Input pulse levels: 0.0V to 3.0V
- \*Input rise and fall times: 5 ns
- \*Input and Output timing reference levels: 1.5V
- \*Output load: 1 TTL gate + 100pF
- \* $V_{CC}=5V\pm10\%$

## Operating Modes

This Table shows the inputs required to control the operating modes of the SRAMs on the PUMA 3S4000.

Mode	$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	$V_{CC}$ Current	I/O Pin	Reference Cycle
Not Selected	1	X	X	$I_{SB}, I_{SB1}$	High Z	-
Read	0	0	1	$I_{CC}$	$D_{OUT}$	Read Cycle
Write	0	1	0	$I_{CC}$	$D_{IN}$	Write Cycle No.1
Write	0	0	0	$I_{CC}$	$D_{IN}$	Write Cycle No.2

$$1 = V_{IH}$$

$$0 = V_{IL}$$

$$X = V_{IL} \text{ or } V_{IH}$$

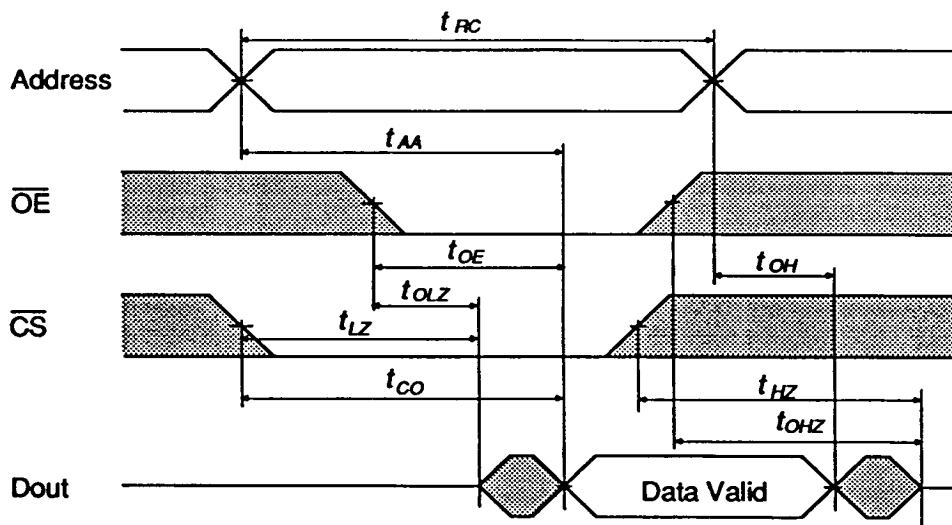
Note:  $\overline{CS}$  is accessed through  $\overline{CS1-4}$ , and  $\overline{WE}$  is accessed through  $\overline{WE1-4}$ . For correct operation,  $\overline{CS1-4}$  must operate simultaneously for 32 bit operation, in pairs for 16 bit operation, or singly for 8 bit operation.  $\overline{WE1-4}$  must also be operated in the same manner.

## Electrical Characteristics & Recommended AC Operating Conditions

### Read Cycle

Parameter	Symbol	70		85		10		12		Units
		min	max	min	max	min	max	min	max	
Read Cycle Time	$t_{RC}$	70	-	85	-	100	-	120	-	ns
Address Access Time	$t_{AA}$	-	70	-	85	-	100	-	120	ns
Chip Select Access Time	$t_{CO}$	-	70	-	85	-	100	-	120	ns
Output Enable to Output Valid	$t_{OE}$	-	35	-	45	-	50	-	60	ns
Output Hold from Address Change	$t_{OH}$	10	-	10	-	10	-	10	-	ns
Chip Selection to Output in Low Z <sup>(3)</sup>	$t_{LZ}$	10	-	10	-	10	-	10	-	ns
Output Enable to Output in Low Z <sup>(3)</sup>	$t_{OLZ}$	5	-	5	-	5	-	5	-	ns
Chip Deselection to Output in High Z <sup>(3)</sup>	$t_{HZ}$	0	25	0	30	0	35	0	45	ns
Output Disable to Output in High Z <sup>(3)</sup>	$t_{OHZ}$	0	25	0	30	0	35	0	45	ns

### Read Cycle Timing Waveform (1,2)



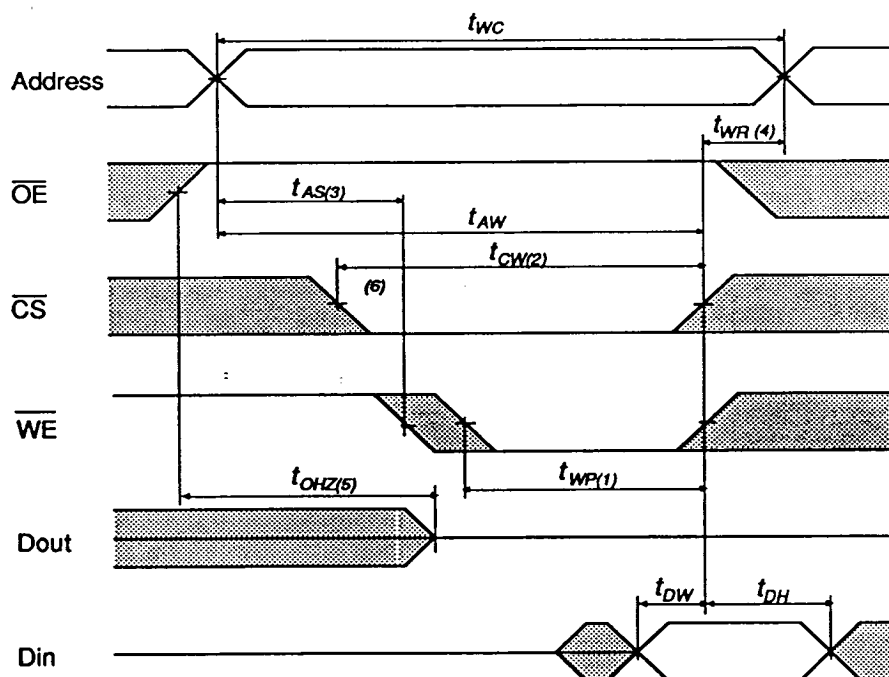
Notes (1)  $\overline{WE}$  is High for Read Cycle.

(2) Address valid prior to or coincident with  $\overline{CS}$  transition Low.

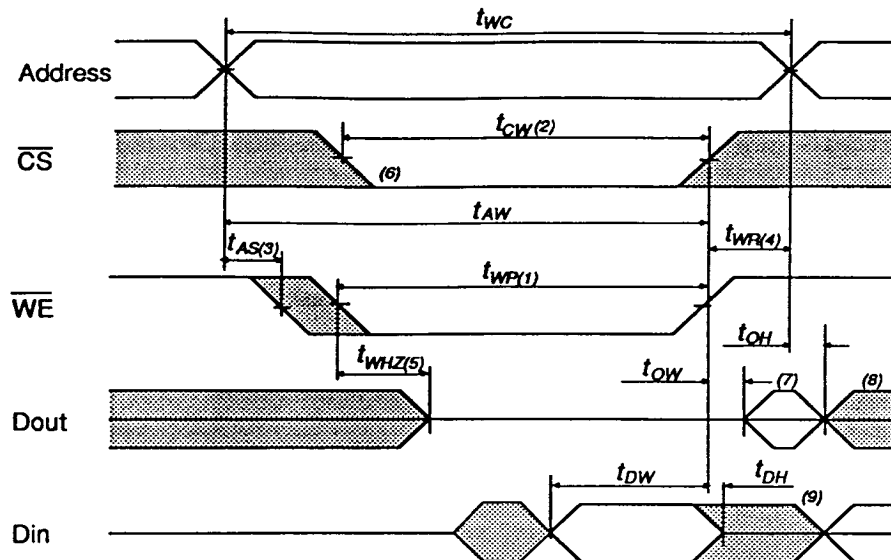
(3)  $t_{LZ}$  and  $t_{OHZ}$  are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels. These parameters are sampled and not 100% tested.

**Write Cycle**

Parameter	Symbol	70		85		10		12		Units
		min	max	min	max	min	max	min	max	
Write Cycle Time	$t_{WC}$	70	-	85	-	100	-	120	-	ns
Chip Selection to End of Write	$t_{CW}$	60	-	75	-	90	-	100	-	ns
Address Valid to End of Write	$t_{AW}$	60	-	75	-	90	-	100	-	ns
Address Setup Time	$t_{AS}$	0	-	0	-	0	-	0	-	ns
Write Pulse Width	$t_{WP}$	55	-	65	-	75	-	85	-	ns
Write Recovery Time	$t_{WR}$	5	-	5	-	5	-	5	-	ns
Write to Output in High Z <sup>(9)</sup>	$t_{WHZ}$	0	25	0	30	0	35	0	40	ns
Data to Write Time Overlap	$t_{DW}$	30	-	35	-	40	-	45	-	ns
Data Hold from Write Time	$t_{DH}$	0	-	0	-	0	-	0	-	ns
Output Active from End of Write	$t_{OW}$	5	-	5	-	5	-	5	-	ns

**Write Cycle No.1 Timing Waveform**

## Write Cycle No.2 Timing Waveform



## AC Characteristics Notes

- (1) A write occurs during the overlap ( $t_{WP}$ ) of a low  $\overline{CS}$  and a low  $\overline{WE}$ .
- (2)  $t_{WR}$  is measured from the earlier of  $\overline{CS}$  or  $\overline{WE}$  going high to the end of write cycle.
- (3) During this period, I/O pins are in the output state. Input signals out of phase must not be applied.
- (4) If the  $\overline{CS}$  low transition occurs simultaneously with the  $\overline{WE}$  low transition or after the  $\overline{WE}$  low transition, outputs remain in a high impedance state.
- (5)  $\overline{OE}$  is continuously low. ( $\overline{OE}=V_H$ )
- (6) Dout is in the same phase as written data of this write cycle.
- (7) Dout is the read data of next address.
- (8) If  $\overline{CS}$  is low during this period, I/O pins are in the output state. Input signals out of phase must not be applied to I/O pins.
- (9)  $t_{WCZ}$  is defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels. This parameters is sampled and not 100% tested.

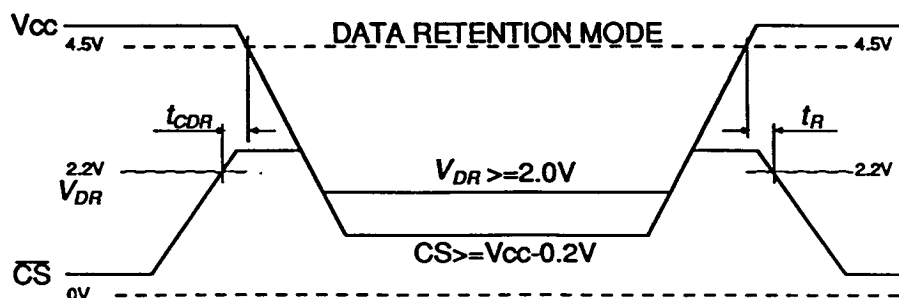
## Low $V_{CC}$ Data Retention Characteristics - L Version Only ( $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ )

Parameter	Symbol	Test Condition	min	typ <sup>(2)</sup>	max	Unit
$V_{CC}$ for Data Retention	$V_{DR}$	$\overline{CS} \geq V_{CC} - 0.2V$	2.0	-	-	V
Data Retention Current	$I_{CCDR}$	$V_{CC} = 3.0V$ , $\overline{CS} \geq 2.8V$ , $0.2V \geq V_H \geq 2.8V$	-	4	200	$\mu A$
$\overline{CS}$ high to Data Retention Time	$t_{CDR}$	See Retention Waveform	0	-	-	ns
Operation Recovery Time	$t_R$	See Retention Waveform	$t_{RC}^{(1)}$	-	-	ns

Notes: (1)  $t_{RC}$  = Read Cycle Time.

(2) Typical figures are measured at  $25^\circ\text{C}$ .

## Low $V_{CC}$ Data Retention Timing Waveform



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**Ordering Information**


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**PUMA 3S4000LI-85**

				Speed	70	= 70 ns
					85	= 85 ns
					10	= 100 ns
					12	= 120 ns
				Temperature range	Blank	= Commercial Temperature
					I	= Industrial Temperature
				Power Consumption	Blank	= Standard power
					L	= Low power
				Memory Type	S4000	= 128K x 32 or 256K x 16 or 512K x 8 SRAM
				Package	PUMA 3	= Plastic Pin Grid Array

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The policy of the company is one of continuous development and while the information presented in this data sheet is believed to be accurate, no liability is assumed for any data contained within. The company reserves the right to make changes without notice at any time.

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